

Docket No.: 09450/100K673-US2  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Patent Application of:  
Masahiko FURUNO et al.

Application No.: 10/771,990

Confirmation No.: 3571

Filed: February 3, 2004

Art Unit: 1725

For: BUMP FORMING METHOD,  
PRESOLDERING TREATMENT METHOD,  
SOLDERING METHOD, BUMP FORMING  
APPARATUS, PRESOLDERING  
TREATMENT DEVICE AND SOLDERING  
APPARATUS

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Examiner: Michael Aboagye

**RESPONSE TO NON-FINAL OFFICE ACTION**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the non-final Office Action dated December 29, 2006, please amend the above-identified U.S. patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 9 of this paper.